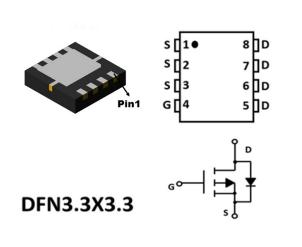
P-Channel Enhancement Mode Field Effect Transistor



Product Summary

- V_{DS} • I_D
- ID
 R_{DS(ON)}(at V_{GS}= -4.5V)
- -55A <8.3mohm

<10mohm

<15mohm

-20V

- R_{DS(ON)}(at V_{GS}= -2.5V)
- R_{DS(ON)}(at V_{GS}= -1.8V)
- 100% UIS Tested
- 100% \bigtriangledown V_{DS} Tested

General Description

- Trench Power LV MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low R_{DS(ON)}

Applications

- High current load applications
- Load switching
- Hard switched and high frequency Circuits
- Uninterruptible power supply

■ Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Parameter		Symbol	Limit	Unit	
Drain-source Voltage		V _{DS}	-20	V	
Gate-source Voltage		V _{GS}	±10	V	
Drain Current	T _A =25℃		55	A	
	T _A =100°C	- I _D -	35		
Pulsed Drain Current ^A		I _{DM}	160	А	
Single Pulse Avalanche Energy ^B		E _{AS}	75	mJ	
Total Power Dissipation	T _C =25℃	P₀	38	W	
	T _A =25℃	F D	3.2		
Thermal Resistance Junction-to-Case		Reuc	3.3	°C/ W	
		R _{0JA}	39	C/ VV	
Junction and Storage Temperature Range		T _J ,T _{STG}	-55~+150	°C	

Ordering Information (Example)

PREFERED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJQ55P02A	F1	Q55P02A	5000	10000	100000	13" reel
1/7						



YJQ55P02A

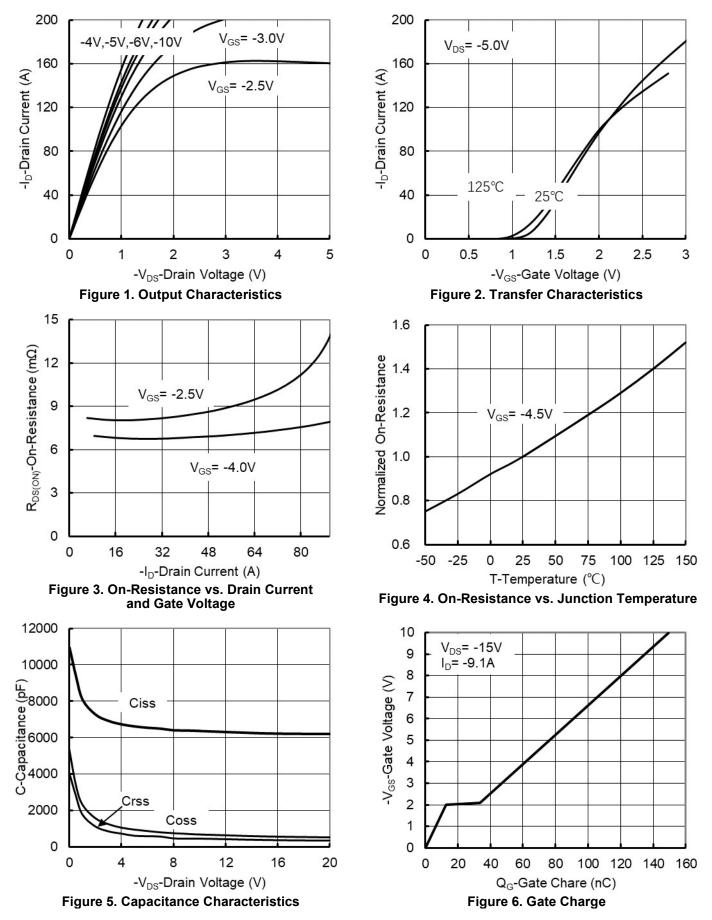
■ Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Тур	Мах	Units
Static Parameter	1 1			I	L	I
Drain-Source Breakdown Voltage	BV _{DSS}	V_{GS} = 0V, I _D =250µA	-20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-20V,V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	$V_{GS}\text{=}\pm10\text{V},V_{DS}\text{=}0\text{V}$			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V_{DS} = V_{GS} , I_D =-250 μ A	-0.4	-0.62	-1.0	V
		V _{GS} = -4.5V, I _D =-15A		6.5	8.3	mΩ
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} = -2.5V, I _D =-10A		8.0	10.0	
		V _{GS} = -1.8V, I _D =-8.0A		10.3	15	
Diode Forward Voltage	V _{SD}	I _S =-20A,V _{GS} =0V		-0.7	-1.2	V
Maximum Body-Diode Continuous Current	Is				-55	А
Dynamic Parameters						
Input Capacitance	C _{iss}			6358		pF
Output Capacitance	C _{oss}	V _{DS} =-10V,V _{GS} =0V,f=1MHZ		690		
Reverse Transfer Capacitance	C _{rss}			477		
Switching Parameters						
Total Gate Charge	Qg			12.7		- nC
Gate-Source Charge	Q _{gs}	V _{GS} =-10V,V _{DS} =-15V,I _D =-9.1A		21		
Gate-Drain Charge	Q _{gd}			149		
Reverse Recovery Charge	Q _{rr}			25.2		
Reverse Recovery Time	t _{rr}	I _F =-6A, di/dt=100A/us		46		
Turn-on Delay Time	t _{D(on)}			11		ns
Turn-on Rise Time	tr	V _{GS} =-10V,V _{DD} =-15V, I _D =-6A		36		
Turn-off Delay Time	t _{D(off)}	R_{GEN} =2.5 Ω		182		
Turn-off fall Time	t _f			191		

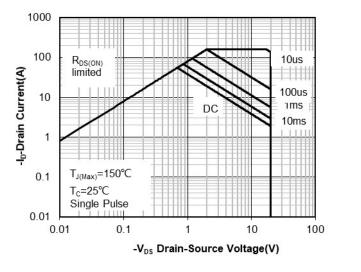
A. Pulse Test: Pulse Width ${\leqslant}300 \text{us,Duty cycle} {\leqslant}2\%.$

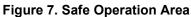
B. $R_{\theta,JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta,JC}$ is guaranteed by design, while $R_{\theta,JA}$ is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.

Typical Performance Characteristics



YJQ55P02A





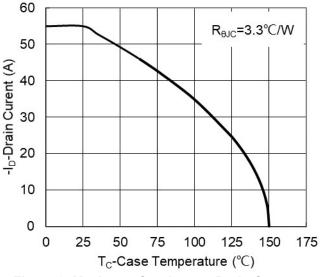


Figure 8. Maximum Continuous Drain Current vs Case Temperature

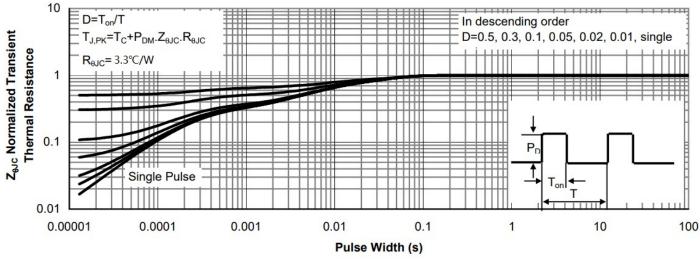
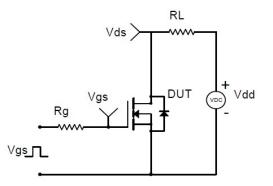
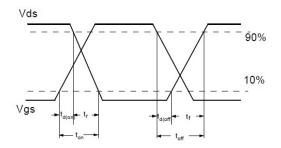


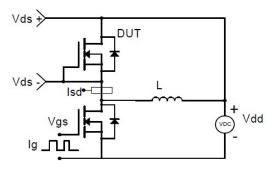
Figure 9. Normalized Maximum Transient Thermal Impedance

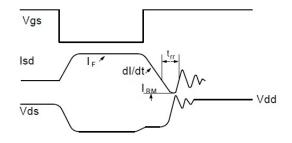
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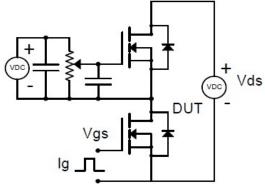


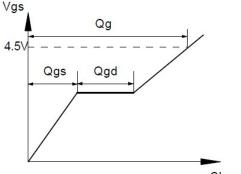
Resistive Switching Test Circuit & Waveforms





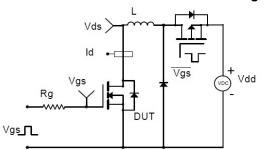
Diode Recovery Test Circuit & Waveforms

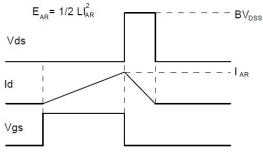




Charge

Gate Charge Test Circuit & Waveform

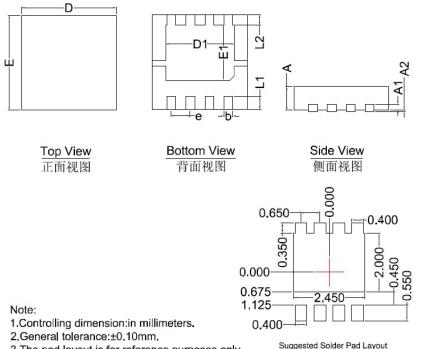




Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

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■DFN3.3X3.3 Package information



SYMBOL	MILLIMETER				
	MIN	NOM	MAX		
D	3.15	3.25	3.35		
E	3.15	3.25	3.35		
A	0.70 0.80 0.90				
A1	0.20 BSC				
A2			0.10		
D1	2.20	2.35	2,50		
E1	1.80	1.90	2.00		
L1	0.35	0.35 0.45 0			
L2	0.35 BSC				
b	0.20	0.30	0.40		
е	0.65 BSC				

3. The pad layout is for reference purposes only.

Suggested Solder Pad Layout Top View

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YJQ55P02A

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